



TSEV01S01C05

SPECIFICATIONS

- **Contact less Temperature Measurement**
- **Small Size**
- **Heat Spreader improves Accuracy**
- **Wide Supply Voltage Range**
- **Digital Interface Bus (SPI)**
- **Connector**
- **Small Field of View**
- **Improved constancy of output signal over distance**

The TSEV01S01C05 is a contact-less temperature measuring system for OEM use based on the detection of infrared radiation.

The TSEV01S01C05 is equipped with an infrared sensor (Thermopile) in front. The Thermopile Sensor has to be pointed at the target object.

The basic working principle is:

- Detection of infrared radiation with a Thermopile sensor, which turns incoming radiation to an analogue voltage
- Determination of sensor temperature using a thermistor
- Calculation of ambient and object temperature using a processing unit
- Providing the ambient and objects temperature at digital output bus (SPI)

The thermopile sensor module is suitable for a wide range of application where non-contact temperature measurement and high accuracy are required.

FEATURES

0°C – 300°C Measurement Range
 Small Size
 Up to 2°C Accuracy
 2mA Current Consumption
 Improved constancy of output signal over distance

APPLICATIONS

Contact less Temperature Measurement
 Climate Control
 Industrial Process Control
 Household Applications

ABSOLUTE MAXIMUM RATINGS

Absolute maximum ratings are limiting values of permitted operation and should never be exceeded under the worst possible conditions either initially or consequently. If exceeded by even the smallest amount, instantaneous catastrophic failure can occur. And even if the device continues to operate satisfactorily, its life may be considerably shortened.

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Supply Voltage	Vccmax	Stabilized supply voltage	-0.3		+16	V
Operating Temperature	Topmax		-10		+85	°C
Storage temperature	Tstor		-40		+85	°C
Humidity	HumL	-40°C - +50°C			85	%
Humidity	HumH	+50°C - +85°C			50	%

OPERATING CONDITIONS

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Supply Voltage	Vcc	Stabilized supply voltage	+3.3		+16	V
Operating Temperature Range	Top		-10		+85	°C
Emission Coefficient	ϵ		0.98			

SENSOR CONDITIONS

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Field of View	FOV 10	Total field of view at 10% signal level		8		°
Field of View	FOV 50	Total field of view at 50% signal level		5		°
Wavelength Range	S		Silicon, no coating			μm

OPERATIONAL CHARACTERISTICS

If not otherwise noted, 5V supply voltage and object with $\epsilon = 0.98$ were applied.

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Object Temperature Range	Tobj		0		300	°C
Resolution	Res				0.1	°C
Supply Current ¹⁾	I	No output load		2		mA
Data Output Rate	Fout			1		Hz
Standard Start-Up Time	tStart				3	s

TOLERANCES

If not otherwise noted, 5V supply voltage and object with $\epsilon = 0.98$ were applied.

Parameter	Symbol	Sensor Temp.	Object Temp.	Max	Unit
Standard Temp. ^{1) 3)}	AccS	$15 < T_{\text{sen}} < 35$	$160 < T_{\text{obj}} < 200$	2	°C
Extended Temp. 1 ^{2) 3)}	AccE1	$T_{\text{sen}} < 15, T_{\text{sen}} > 35$	$160 < T_{\text{obj}} < 200$	3	°C
Extended Temp. 2 ^{2) 3)}	AccE2	$15 < T_{\text{sen}} < 35$	$T_{\text{obj}} < 160, T_{\text{obj}} > 200$	3	°C
Extended Temp. 3 ^{2) 3)}	AccE3	$T_{\text{sen}} < 15, T_{\text{sen}} > 35$	$T_{\text{obj}} < 160, T_{\text{obj}} > 200$	4	°C

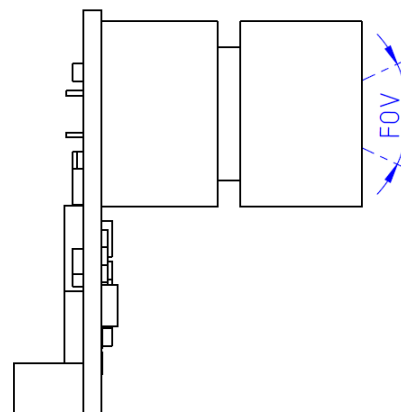
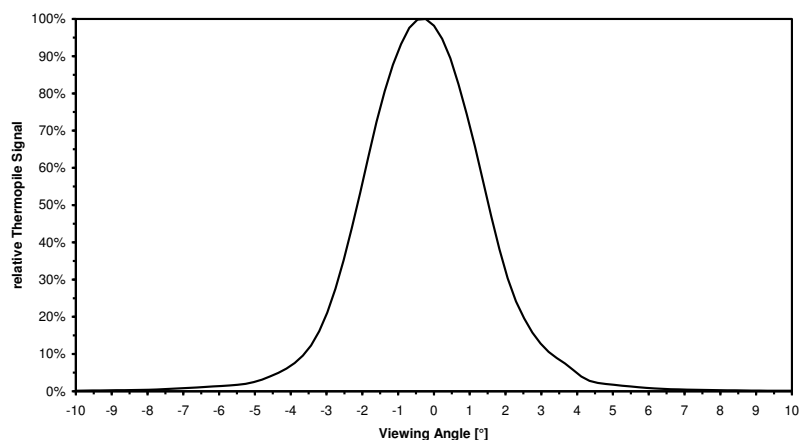
OTHER TEMPERATURE RANGES AND ACCURACIES ARE AVAILABLE ON REQUEST.

¹⁾ Proved while production

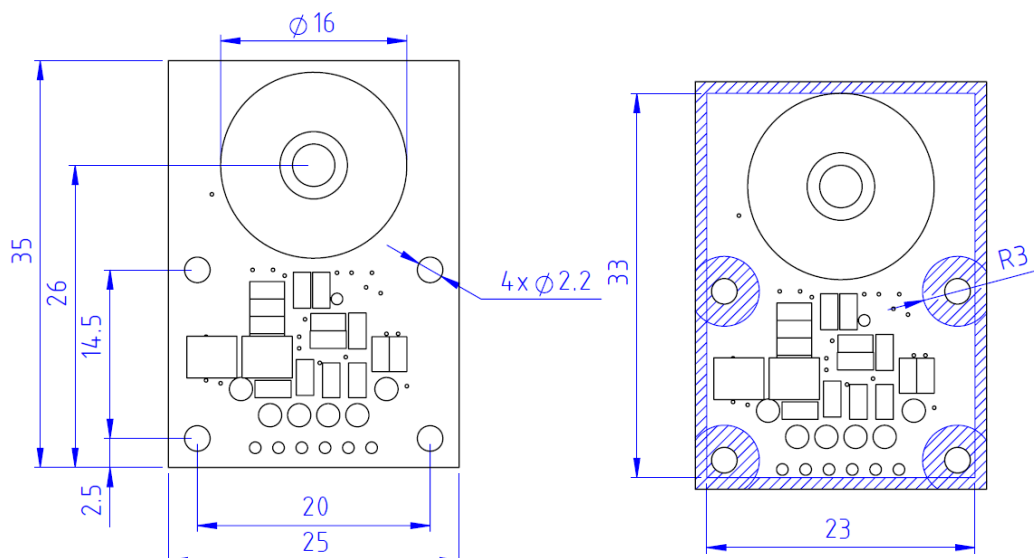
²⁾ Proved by design

³⁾ Valid for a distance of 100mm and black body size of 150mm x 150mm

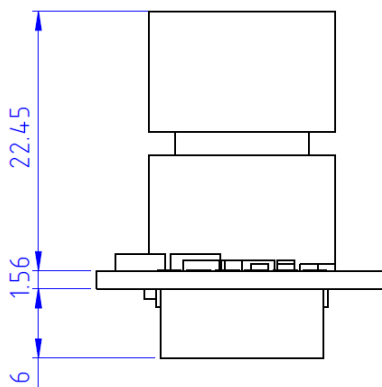
SENSOR FIELD OF VIEW



Mechanical Dimensions



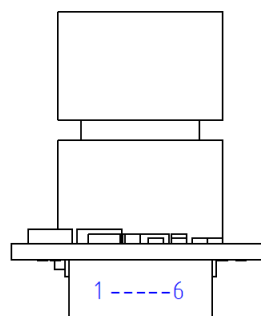
Only use hatched areas for mechanical assembly (screws, nuts, etc).



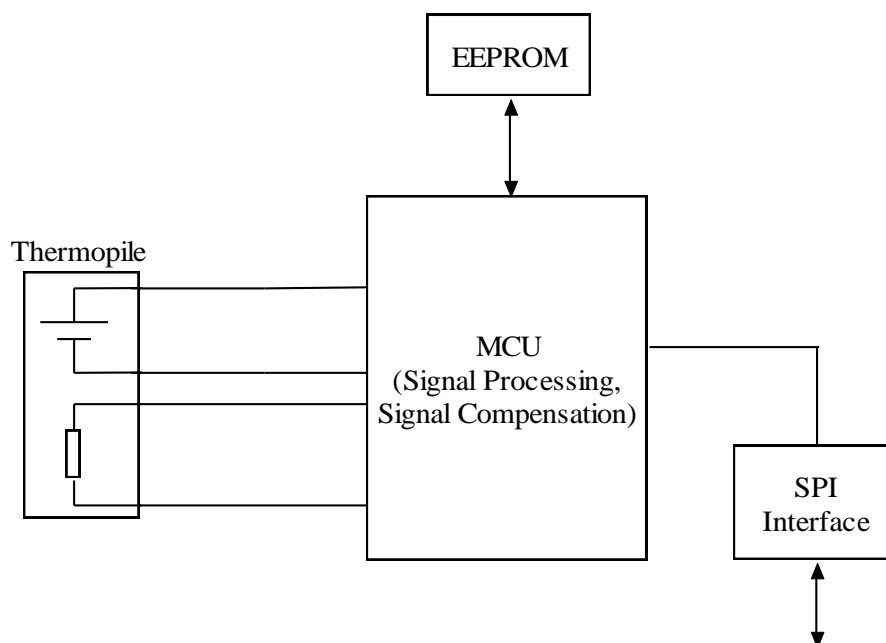
TERMINALS

Connector: JST PHR-6

Pin	Name	Description	Type
1	VDD	Supply Voltage	Supply
2	GND	Ground	Supply
3	SCL	SPI Clock	Interface
4	MISO	SPI Master In /	Interface
5	MOSI	SPI Master Out /	Interface
6	SCE	SPI Chip Enable	Interface



BLOCK DIAGRAM



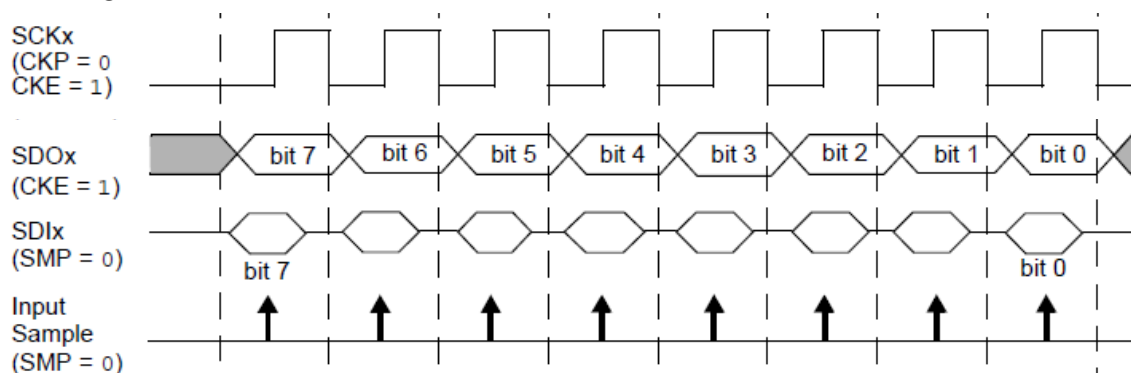
INTERFACE

PARAMETER

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Baudrate	FSPI		10		100	kHz
Data Bits				8		
Chip Select				Yes		
Input Voltage Low					0.9	V
Input Voltage High		V _{CC} = 3.3V	2.1			V
Output Voltage Low		1mA			0.3	V
Output Voltage High		V _{CC} = 3.3V, 1mA	3.0			V

SIGNAL DESCRIPTION

- SCE (Chip Select) 0 = Enable, 1 = Disable
- CKP 0
- CKE 1



SAMPLE CODE

Sample Code for sending 8 bits and reading 8 bits while sending 8 clocks.

```
// Setting directions
    TRISC4 = 1;    // SDI = Input
    TRISC5 = 0;    // SDO = Output
    TRISC3 = 0;    // SCL = Output

// Reset SPI Lines
    RC5 = 0; // SDO
    RC3 = 0; // SCL
    for (c = 0; c < 8; c++)
    {
        cReceive = cReceive << 1;    // Shift Receive Register
        RC3 = 0;                      // SCL = 0
        RC5 = (cTransmit >> (7 - c)); // Output next Bit on SDO
        RC3 = 1;                      // SCL = 1
        cReceive = cReceive | RC4;    // Input next Bit on SDI
    }
    RC3 = 0;
    RC5 = 0;

return cReceive;
```

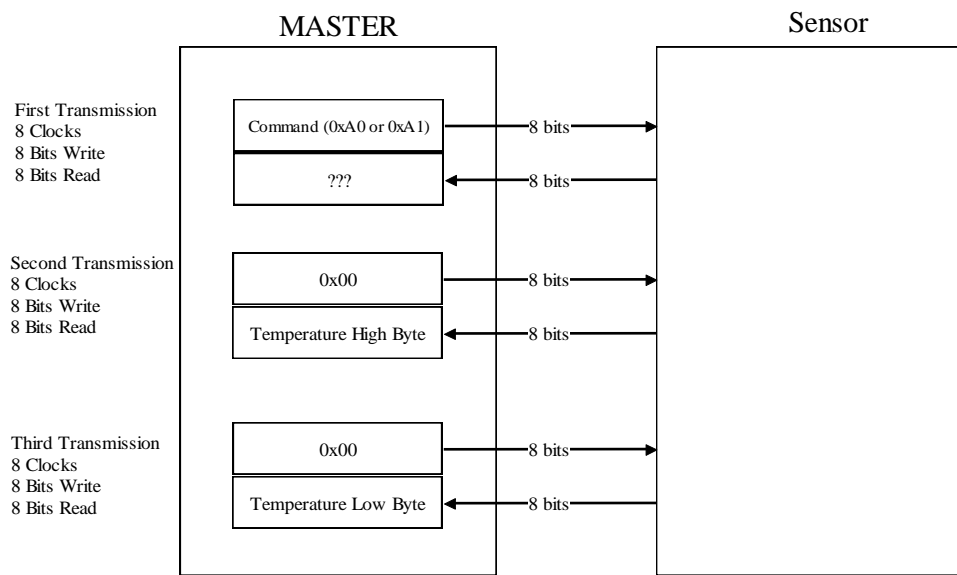
AMBIENT AND OBJECT TEMPERATURE MEASUREMENT

Please refer following table for SPI commands to read object temperature and ambient temperature. Both values are transmitted in hundredth of degrees.

Com	Description	Reply	Bytes
0xA0	Sensor Temperature	Sensor temperature in hundredth of degrees Celsius	2
0xA1	Object Temperature	Object temperature in hundredth of degrees Celsius	2

SEQUENCE OF TRANSMISSION

Enable SCE (SCE=0) before transmission of “Command”. Release SCE (SCE=1) after reading last byte.



EXAMPLE OF TEMPERATURE CALCULATION

For reading object temperature send: 0xA1

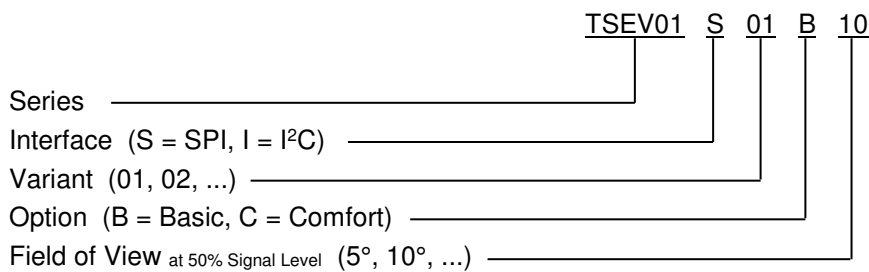
Return values i.e.:

Byte(0) = ??? discard reading

Byte(1) = 0x1A (=26)

Byte(2) = 0xB0 (=176)

$T_{obj} = (256 * \text{Byte}(1) + \text{Byte}(2)) / 100 = (256 * 26 + 176) / 100 = 68.32^{\circ}\text{C}$

NAMING CONVENTION**ORDER INFORMATION**

Please order this product using following:

Part Number
G-TPMO-025

Part Description
TSEV01S01C05

EMC

Due to the use of these modules for OEM application no CE declaration is done.

Especially line coupled disturbances like surge, burst, HF etc. cannot be removed by the module due to the small board area and low price feature. There is no protection circuit against reverse polarity or over voltage implemented.

The module will be designed using capacitors for blocking and ground plane areas in order to prevent wireless coupled disturbances as good as possible.

Definitions and Disclaimers

- Application information – Applications that are described herein for any of these products are for illustrative purpose only. MEAS Deutschland GmbH makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.
- Life support applications – These products are not designed for use in life support appliances, devices, or systems where malfunctions of these products can reasonably be expected to result in personal injury.
MEAS Deutschland GmbH customers using or selling this product for use in such applications do so at their own risk and agree to fully indemnify MEAS Deutschland GmbH for any damages resulting from such improper use or sale.

NORTH AMERICA

Measurement Specialties, Inc.,
a TE Connectivity Company
910 Turnpike Road
Shrewsbury, MA 01545
Tel: 1-508-842-0516
Fax: 1-508-842-0342
Sales email:
temperature.sales.amer@meas-spec.com

EUROPE

Measurement Specialties (Europe), Ltd.,
a TE Connectivity Company
Deutschland GmbH
Hauert 13
44277 Dortmund
Tel: +49 (0) 231/9740-0
Fax: +49 (0) 231/9740-20
Sales email:
info.de@meas-spec.com

ASIA

Measurement Specialties (China), Ltd.,
a TE Connectivity Company
No. 26 Langshan Road
Shenzhen High-Tech Park (North)
Nanshan District, Shenzhen 518057
China
Tel: +86 755 3330 5088
Fax: +86 755 3330 5099
Sales email:
temperature.sales.asia@meas-spec.com

TE.com/sensorsolutions

Measurement Specialties, Inc., a TE Connectivity company.

Measurement Specialties, TE Connectivity, TE Connectivity (logo) and EVERY CONNECTION COUNTS are trademarks. All other logos, products and/or company names referred to herein might be trademarks of their respective owners.

The information given herein, including drawings, illustrations and schematics which are intended for illustration purposes only, is believed to be reliable. However, TE Connectivity makes no warranties as to its accuracy or completeness and disclaims any liability in connection with its use. TE Connectivity's obligations shall only be as set forth in TE Connectivity's Standard Terms and Conditions of Sale for this product and in no case will TE Connectivity be liable for any incidental, indirect or consequential damages arising out of the sale, resale, use or misuse of the product. Users of TE Connectivity products should make their own evaluation to determine the suitability of each such product for the specific application.

© 2015 TE Connectivity Ltd. family of companies All Rights Reserved.